

Title (en)

UNIVERSAL ENERGY CONDITIONING INTERPOSER WITH CIRCUIT ARCHITECTURE

Title (de)

UNIVERSELLES ENERGIEANPASSUNGSZWISCHENSTÜCK MIT SCHALTUNGSARCHITEKTUR

Title (fr)

DISPOSITIF D'INTERPOSITION UNIVERSEL DESTINE AU CONDITIONNEMENT D'ENERGIE ET MUNI D'UNE ARCHITECTURE DE CIRCUIT

Publication

EP 1206825 A1 20020522 (EN)

Application

EP 00953814 A 20000803

Priority

- US 0021178 W 20000803
- US 14698799 P 19990803
- US 16503599 P 19991112
- US 46021899 A 19991213
- US 18010100 P 20000203
- US 18532000 P 20000228
- US 20032700 P 20000428
- US 20386300 P 20000512
- US 57960600 A 20000526
- US 59444700 A 20000615
- US 21531400 P 20000630

Abstract (en)

[origin: WO0110000A1] The present invention relates to an interposer substrate (310) for interconnecting between active electronic componentry such as but not limited to a single or multiple integrated circuit (4100) chips in either a single or a combination, and elements that could comprise of a mounting substrate, substrate module, a printed circuit board, integrated circuit chips or other substrates containing conductive energy pathways that service an energy utilizing load and leading to and from an energy source.

IPC 1-7

H02H 9/00; **H03H 1/00**

IPC 8 full level

H01L 23/32 (2006.01); **H01L 23/498** (2006.01); **H01L 23/50** (2006.01); **H01L 23/552** (2006.01); **H03H 1/00** (2006.01); **H05K 1/14** (2006.01); **H05K 1/16** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP)

H01L 23/49827 (2013.01); **H01L 23/50** (2013.01); **H01L 23/552** (2013.01); **H01L 2223/6622** (2013.01); **H01L 2224/05571** (2013.01); **H01L 2224/05573** (2013.01); **H01L 2224/16225** (2013.01); **H01L 2224/16235** (2013.01); **H01L 2224/16265** (2013.01); **H01L 2924/00014** (2013.01); **H01L 2924/01019** (2013.01); **H01L 2924/01078** (2013.01); **H01L 2924/01079** (2013.01); **H01L 2924/01087** (2013.01); **H01L 2924/01322** (2013.01); **H01L 2924/15311** (2013.01); **H01L 2924/3011** (2013.01); **H01L 2924/3025** (2013.01); **H05K 1/141** (2013.01); **H05K 1/162** (2013.01); **H05K 3/3436** (2013.01)

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)

WO 0110000 A1 20010208; AU 6619800 A 20010219; CN 1377516 A 20021030; EP 1206825 A1 20020522; EP 1206825 A4 20040317; IL 147848 A0 20020814; JP 2003506878 A 20030218

DOCDB simple family (application)

US 0021178 W 20000803; AU 6619800 A 20000803; CN 00813750 A 20000803; EP 00953814 A 20000803; IL 14784800 A 20000803; JP 2001514521 A 20000803